

**描述 / Descriptions**

2.0A 表面贴装玻璃钝化整流桥，薄型 ABF 封装。  
2.0A Surface Mount Glass Passivated Bridge Rectifier, ABF thin package.

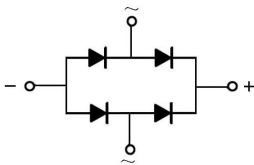
**特征 / Features**

玻璃钝化芯片，反向电压：1000V，正向电流：2.0A，快速反向恢复时间，适用于表面贴装。无卤产品。  
Glass Passivated Chip Junction, Reverse Voltage: 1000V, Forward Current: 2.0A, Fast reverse recovery time, Designed for Surface Mount Application. Halogen free product.

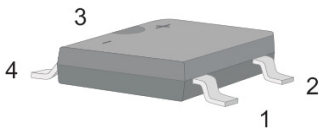
**用途 / Applications**

一般用途。  
General purpose.

**内部等效电路 / Equivalent Circuit**

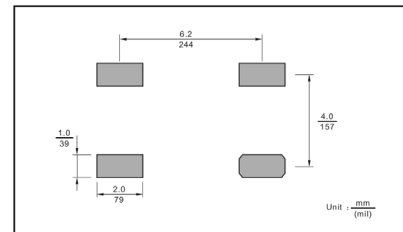


**引脚排列 / Pinning**



PIN	DESCRIPTION
1	Input Pin ( ~ )
2	Input Pin ( ~ )
3	Output Anode ( + )
4	Output Cathode ( - )

The recommended mounting pad size



**印章代码 / Marking**

见印章说明。See Marking Instructions.

**极限参数 / Absolute Maximum Ratings(Ta=25°C)**

参数 Parameter	符号 Symbol	数值 Rating	单位 Unit
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	1000	V
Maximum RMS Voltage	$V_{RMS}$	700	V
Maximum DC Blocking Voltage	$V_{DC}$	1000	V
Average Rectified Output Current at $T_c = 125^\circ\text{C}$	$I_o$	2.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	$I_{FSM}$	60	A
Typical Junction Capacitance <sup>(Note1)</sup>	$C_j$	40	pF
Typical Thermal Resistance <sup>(Note2)</sup>	$R_{\theta JA}$	70	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	$T_j, T_{stg}$	-55~150	$^\circ\text{C}$

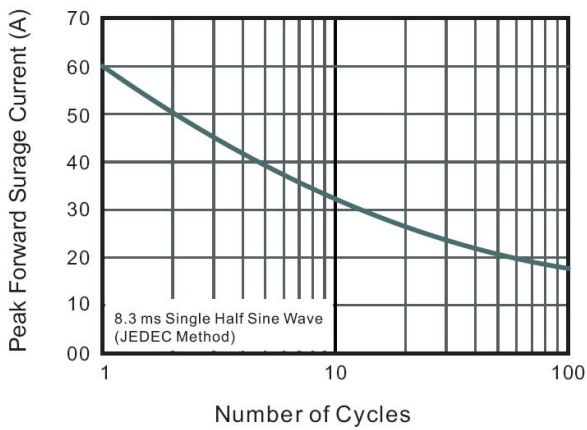
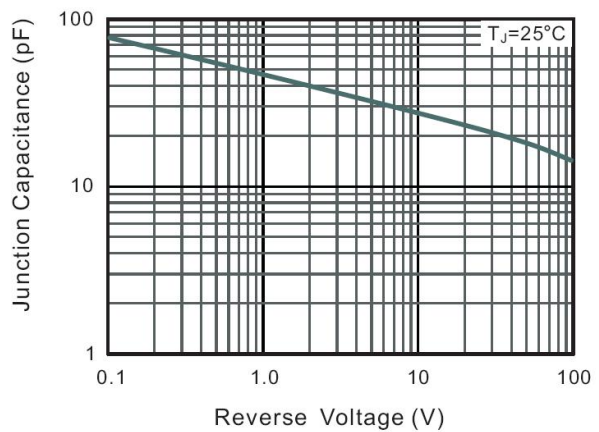
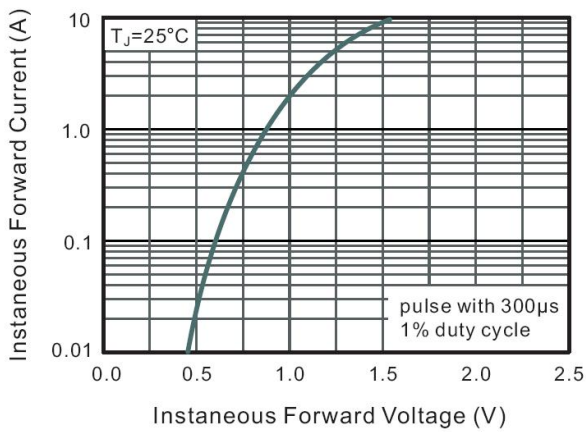
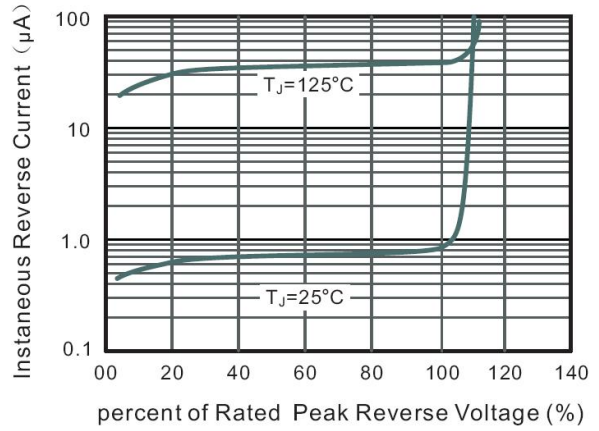
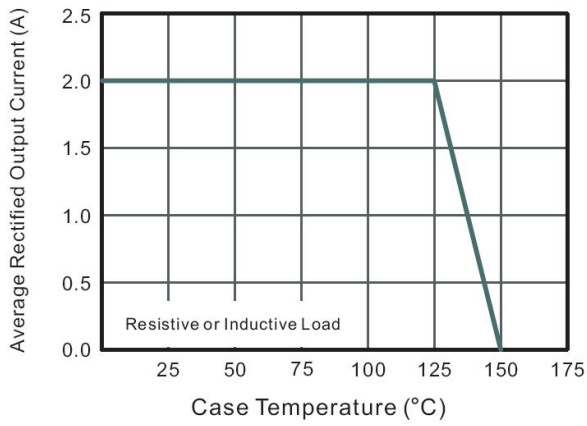
Note:

- 1.Measured at 1MHz and applied reverse voltage of 4 V D.C.
2. Mounted on glass epoxy PC board with 4×1.0" X 1.0" (2.54 X 2.54 cm) copper pad.

**电性能参数 / Electrical Characteristics(Ta=25°C)**

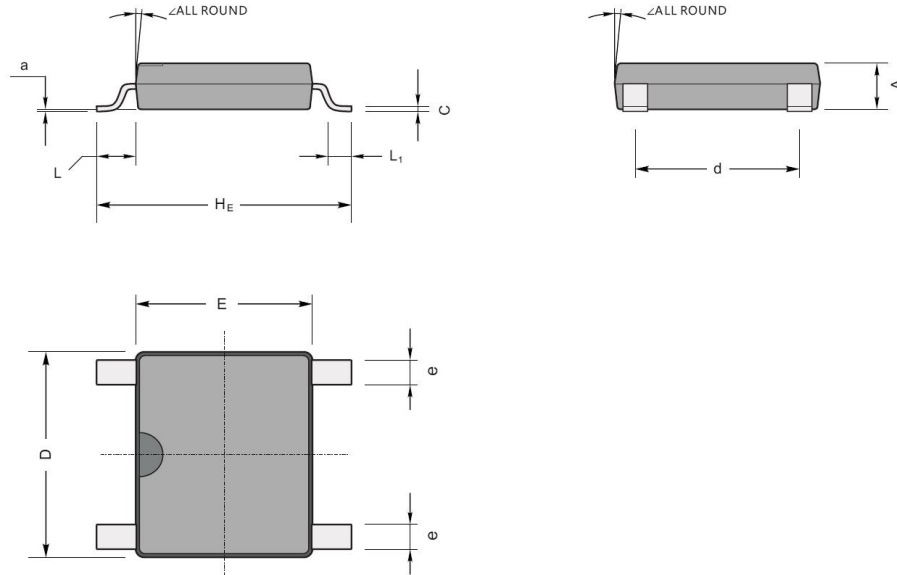
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Forward Voltage per element	$V_F$	$I_F=2.0\text{A}$	1.3	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	$I_R$	$T_a=25^\circ\text{C}$	5.0	$\mu\text{A}$
		$T_a=125^\circ\text{C}$	50	$\mu\text{A}$
Maximum Reverse Recovery Time	$t_{rr}$	$I_F=0.5\text{A}$ $I_R=1.0\text{A}$ $I_{rr}=0.25\text{A}$	200	ns

电参数曲线图 / Electrical Characteristic Curve



外形尺寸图 / Package Dimensions

ABF



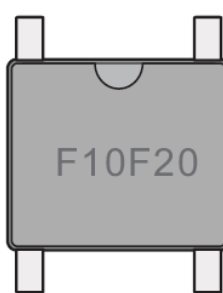
ABF mechanical data

UNIT		A	C	D	E	$H_E$	d	e	L	$L_1$	a	$\angle$
mm	max	1.2	0.22	5.2	4.5	6.4	4.2	0.7	0.95	0.6	0.2	7°
	min	1.0	0.15	4.9	4.2	6.0	3.8	0.5				
mil	max	47	8.7	205	177	252	165	28	37	24	8	
	min	39	5.9	193	166	236	150	20				

印章说明 / Marking Instructions

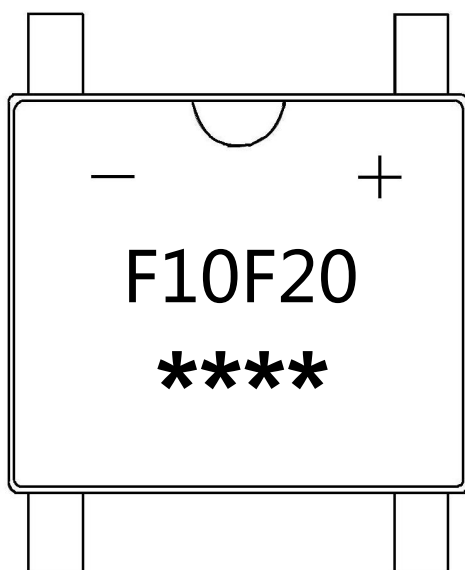
## Marking

Type number	Marking code
FTB10F-20	F10F20

The diagram shows a rectangular component with four pins (two on the top and two on the bottom). The marking code 'F10F20' is printed on the front face of the component.

印章说明 / Marking Instructions



说明：

F10F20： 为型号代码

\*\*\*\*： 为生产批号追溯码，第1个\*为年月代码，后面3个\*为当月小批号代码

Note:

F10F20： Product Type Code

\*\*\*\*： Lot No. Code , The 1st \* means:YM Code , The last 3 \* means:little Lot  
No Code

**回流焊温度曲线图(无铅) / Temperature Profile for IR Reflow Soldering(Pb-Free)**



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 245±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:245±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

**耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions**

温度：260±5°C

时间：10±1 sec.

Temp.:260±5°C

Time:10±1 sec

**包装规格 / Packaging SPEC.**

卷盘包装 / REEL

Package Type 封装形式	Units 包装数量					Dimension 包装尺寸 (unit: mm <sup>3</sup> )		
	Units/Reel 只/卷盘	Reels/Inner Box 卷盘/盒	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Reel	Inner Box 盒	Outer Box 箱
ABF	5000	2	10000	5	50000	13" × 15	336X336X40	380X335X366

**使用说明 / Notices**